



Material Content Data Sheet



Sales Product Name		ESD102-U1-02ELS E6327		Issued		19. January 2018		
MA#		MA001188084						
Package		PG-TSSLP-2-3		Weight*		0.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.17		1708	
	noble metal	gold	7440-57-5	0.001	0.66		6618	
	inorganic material	silicon	7440-21-3	0.010	4.91	5.74	49052	57378
leadframe	non noble metal	nickel	7440-02-0	0.108	52.91	52.91	529087	529087
wire	non noble metal	copper	7440-50-8	0.001	0.69	0.69	6926	6926
encapsulation	organic material	carbon black	1333-86-4	0.000	0.19		1943	
	plastics	epoxy resin	-	0.012	5.63		56311	
	inorganic material	silicondioxide	60676-86-0	0.067	33.01	38.83	330098	388352
leadfinish	noble metal	gold	7440-57-5	0.004	1.81	1.81	18052	18052
plating	noble metal	palladium	7440-05-3	0.000	0.01		78	
	noble metal	gold	7440-57-5	0.000	0.01	0.02	127	205
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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